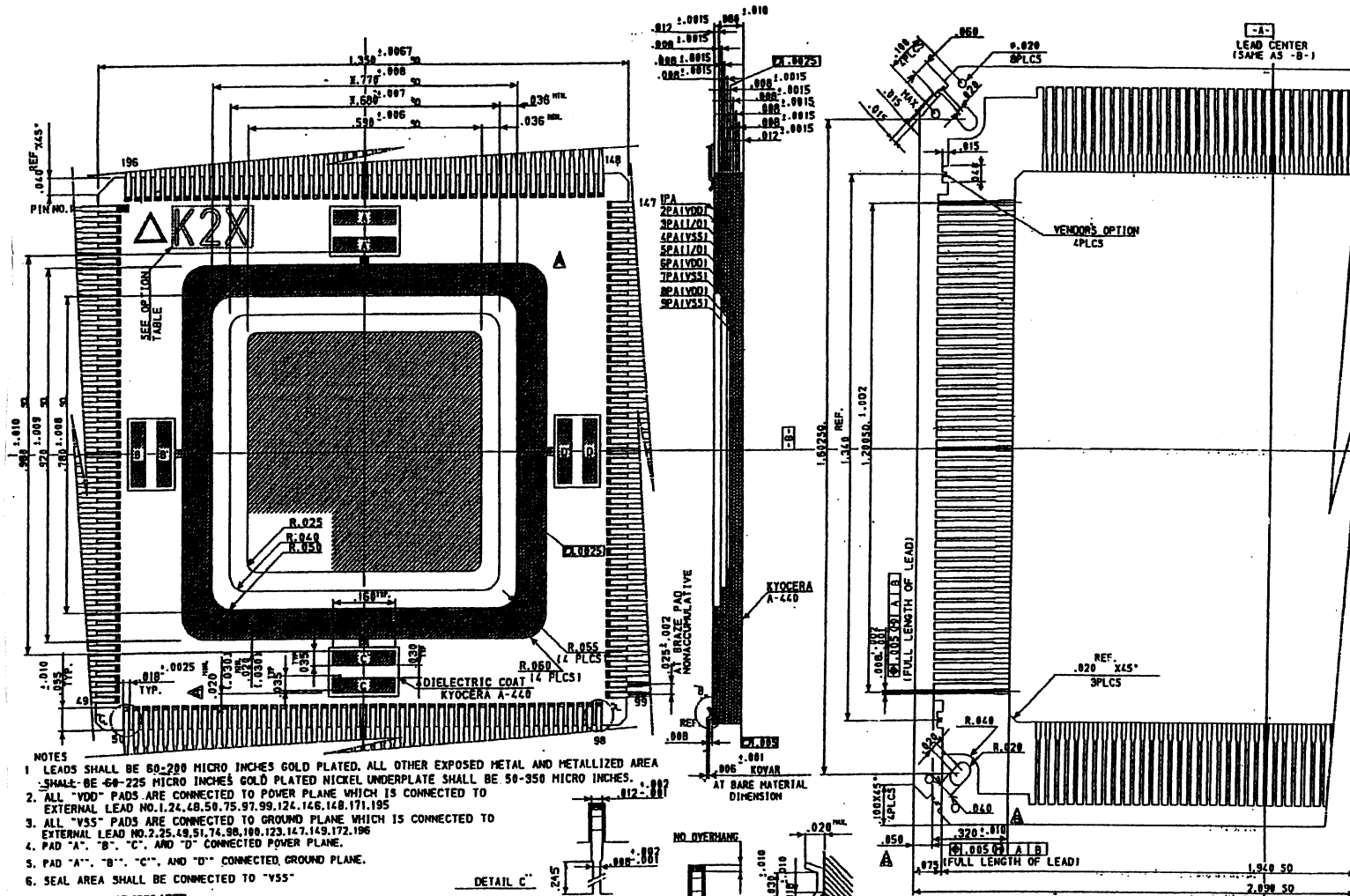


SSM P/N CCF19612



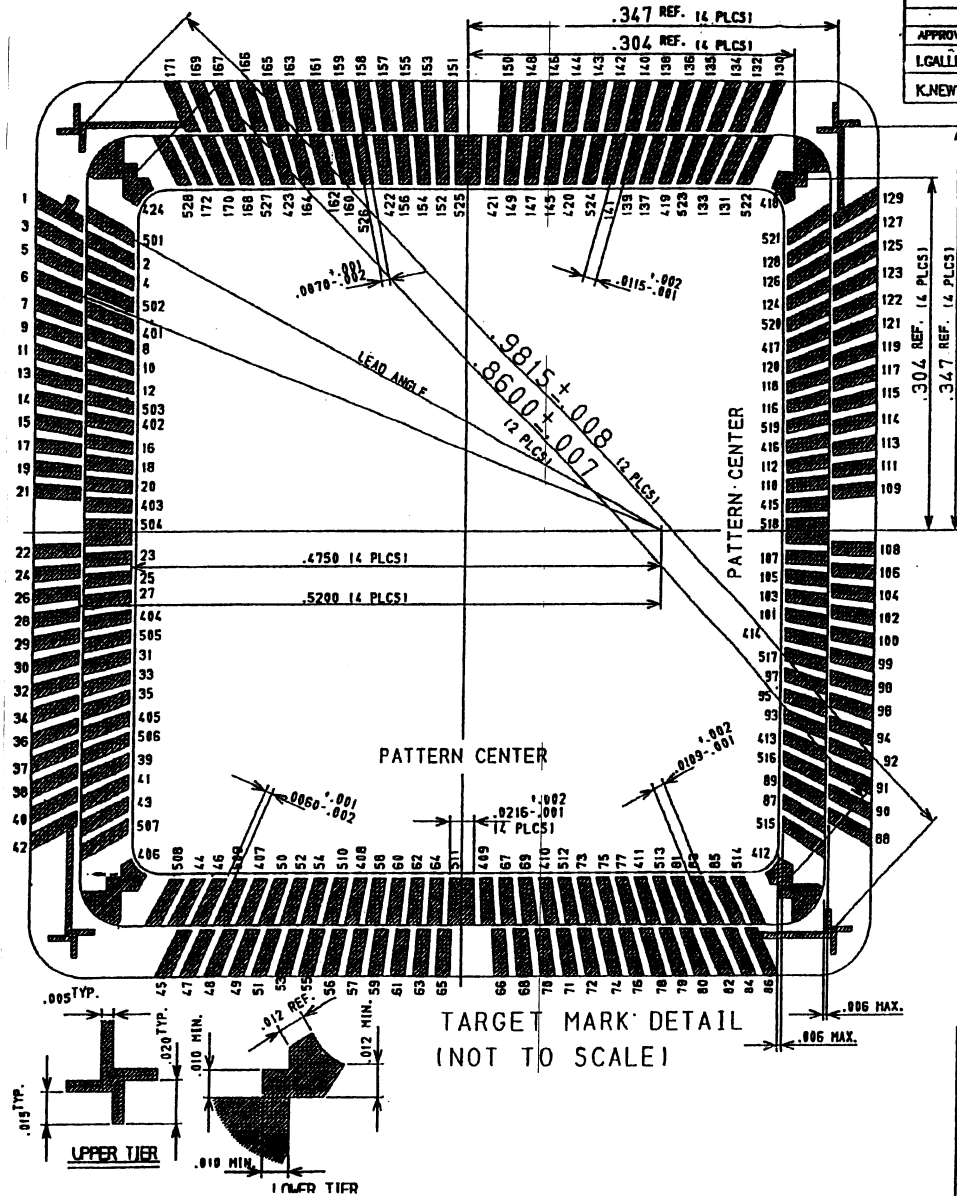
- NOTES
- LEADS SHALL BE 60-200 MICRO INCHES GOLD PLATED. ALL OTHER EXPOSED METAL AND METALLIZED AREA SHALL BE 60-225 MICRO INCHES GOLD PLATED NICKEL UNDERPLATE SHALL BE 50-350 MICRO INCHES.
 - ALL "VDD" PADS ARE CONNECTED TO POWER PLANE WHICH IS CONNECTED TO EXTERNAL LEAD NO.1,24,48,50,75,97,99,124,146,148,171,195
 - ALL "VSS" PADS ARE CONNECTED TO GROUND PLANE WHICH IS CONNECTED TO EXTERNAL LEAD NO.2,25,49,51,74,98,100,123,147,149,172,196
 - PAD "A", "B", "C", AND "D" CONNECTED POWER PLANE.
 - PAD "A", "B", "C", AND "D" CONNECTED GROUND PLANE.
 - SEAL AREA SHALL BE CONNECTED TO "VSS"
 - DIE ATTACH PAD ISOLATED.
 - LEAD PULL STRENGTH TO BE 0.5 LBS. MIN. PERPENDICULAR PULL.
 - INDICATES DIMENSION OF THE TOP LAYER.
 - LEAD RESISTANCE:
 - B/P PAD "VSS" — 0.20 OHMS MAX.
 - "VDD" — 0.25 OHMS MAX.
 - ALL OTHERS — 0.70

UNLESS OTHERWISE SPECIFIED DIMENSIONAL TOLERANCES		TITLE	
DRAFTER	DATE	196 CERAMIC LEADED CHIP CARRIER	
ENGINEER	DATE	CODE DP	CAWTY 0.590
APPROVAL	DATE	DWG NO.	REV. 1
APPROVAL	DATE	SCALE	SHEET 1 of 3



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SSM P/N CCF19612



REVISIONS			
SIGNATURE AND DATE		DESCRIPTION	
APPROVAL	EDM NO.	DATE	DESCRIPTION
L.GALLEGOS	91563	07-20-91	INITIAL RELEASE
K.NEWMAN		10-28-91	REPLACE OPTION -21 WITH -22.

LEAD DATA (UPPER TIER)									
LEAD NUMBER	LEAD ANGLE	LEAD CENTER	LEAD START	LEAD END	LEAD WIDTH				
22	65	109	51	1.674	0.0152				
21	24	63	65	105	109	150	153	3.711	0.0331
19	26	61	69	104	111	148	155	5.744	0.0523
17	28	59	70	102	113	145	157	7.771	0.0710
15	29	57	71	100	114	144	158	9.790	0.0697
14	30	56	72	99	115	143	159	11.790	0.1065
13	32	55	74	98	117	142	161	13.793	0.1277
11	32	53	76	96	119	140	163	15.772	0.1459
9	35	51	78	94	121	138	165	17.733	0.1663
7	37	49	79	92	122	136	166	19.674	0.1859
6	38	48	80	91	123	135	167	21.593	0.2048
5	40	47	82	90	125	134	169	23.488	0.2230
3	42	45	84	88	127	132	171	25.357	0.2404
1	44	43	86	86	129	130	173	27.199	0.2572

LEAD DATA (LOWER TIER)											
LEAD NUMBER	LEAD ANGLE	LEAD CENTER	LEAD START	LEAD END	LEAD WIDTH						
504	504	511	516	516	525	525	0.655	0.0054	0.0000	0.0106	
493	23	62	409	107	415	421	151	2.693	0.0223	0.0169	0.0276
20	25	62	67	105	110	149	154	4.728	0.0393	0.0338	0.0448
18	27	60	69	103	112	147	156	6.759	0.0563	0.0506	0.0616
16	28	58	71	101	114	145	158	8.783	0.0732	0.0675	0.0785
402	505	408	512	414	519	420	526	10.797	0.0906	0.0851	0.0961
503	31	510	73	517	116	524	160	12.799	0.1079	0.1023	0.1133
12	33	52	75	97	118	141	162	14.785	0.1254	0.1198	0.1308
10	35	52	77	95	120	139	164	16.755	0.1430	0.1373	0.1483
8	405	50	411	98	417	437	423	18.707	0.1608	0.1550	0.1665
401	506	407	513	413	520	419	527	20.637	0.1789	0.1731	0.1847
502	39	509	81	516	124	523	168	22.544	0.1972	0.1913	0.2029
4	41	45	83	89	126	133	170	24.426	0.2157	0.2097	0.2217
2	43	44	85	87	128	131	172	26.281	0.2345	0.2285	0.2407
501	507	508	514	515	521	522	528	28.108	0.2537	0.2475	0.2599
424	406	406	412	412	418	418	424	32.170	0.2893	0.2827	0.2954

VDD 401-424
VSS 501-528

UNLESS OTHERWISE SPECIFIED DIMENSIONAL TOLERANCES		TITLE	
FRAC	DEC	196 CERAMIC LEADED CHIP CARRIER	
±.001	±.005	CODE D/P	CAVITY 0.500
DATE	DATE	DWG NO.	REV.
10-16-91		JA01-000183-22	1
SCALE	SCALE	1 SHEET	



SSM P/N CCF19612

REVISIONS			
SIGNATURE AND DATE			DESCRIPTION
APPROVAL	ECN NO.	DATE	
L.GALLEGOS	91563	07-20-91	INITIAL RELEASE
K.NEWMAN		10-28-91	REPLACE OPTION -21 WITH -22.

LEAD/BOND INTERCONNECTION TABLE

LEAD	BOND	LEAD	BOND	LEAD	BOND	LEAD	BOND	LEAD	BOND	LEAD	BOND	LEAD	BOND	LEAD	BOND	LEAD	BOND
1	VDD	27	23	53	45	79	69	105	91	131	115	157	137	183	161		
2	VSS	28	24	54	46	80	70	106	92	132	116	158	138	184	162		
3	1	29	25	55	47	81	71	107	93	133	117	159	139	185	163		
4	2	30	26	56	48	82	72	108	94	134	118	160	140	186	164		
5	3	31	27	57	49	83	73	109	95	135	119	161	141	187	165		
6	4	32	28	58	50	84	74	110	96	136	120	162	142	188	166		
7	5	33	29	59	51	85	75	111	97	137	121	163	143	189	167		
8	6	34	30	60	52	86	76	112	98	138	122	164	144	190	168		
9	7	35	31	61	53	87	77	113	99	139	123	165	145	191	169		
10	8	36	32	62	54	88	78	114	100	140	124	166	146	192	170		
11	9	37	33	63	55	89	79	115	101	141	125	167	147	193	171		
12	10	38	34	64	56	90	80	116	102	142	126	168	148	194	172		
13	11	39	35	65	57	91	81	117	103	143	127	169	149	195	VDD		
14	12	40	36	66	58	92	82	118	104	144	128	170	150	196	VSS		
15	13	41	37	67	59	93	83	119	105	145	129	171	VDD				
16	14	42	38	68	60	94	84	120	106	146	VDD	172	VSS				
17	15	43	39	69	61	95	85	121	107	147	VSS	173	151				
18	16	44	40	70	62	96	86	122	108	148	VDD	174	152				
19	17	45	41	71	63	97	VDD	123	VSS	149	VSS	175	153				
20	18	46	42	72	64	98	VSS	124	VDD	150	130	176	154				
21	19	47	43	73	65	99	VDD	125	109	151	131	177	155				
22	20	48	VDD	74	VSS	100	VSS	126	110	152	132	178	156				
23	21	49	VSS	75	VDD	101	87	127	111	153	133	179	157				
24	VDD	50	VDD	76	66	102	88	128	112	154	134	180	158				
25	VSS	51	VSS	77	67	103	89	129	113	155	135	181	159				
26	22	52	44	78	68	104	90	130	114	156	136	182	160				

VDD : 401-424
VSS : 501-528

UNLESS OTHERWISE SPECIFIED DIMENSIONAL TOLERANCES		TITLE	
DRAYER	DATE	196 CERAMIC LEADED CHIP CARRIER	
DESIGNER	DATE	CODE DP	CAVITY 0.590
APPROVAL	DATE	DWG NO.	JAO1-000183-22
APPROVAL	DATE	REV.	1
		SCALE	1 SHEET

